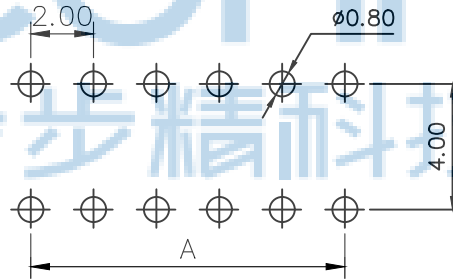
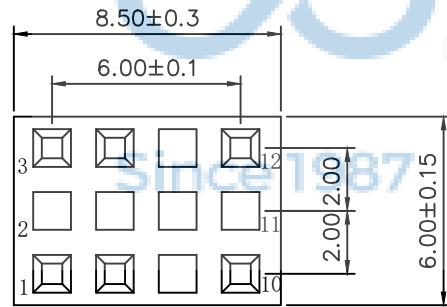
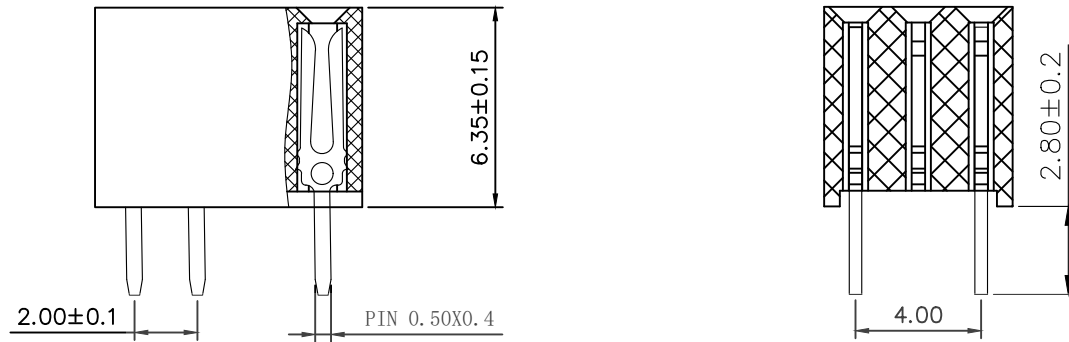


REV.	ECN NO	CONTENT	DATE	ENGINEER
A0		Initial release	/	SGF

## SPECIFICATIONS

Current Rating: 1.5 Amps  
 Insulation Resistance: 1000MΩ Min  
 Contact Resistance: 20mΩ Max  
 Withstanding Voltage: AC 500V  
 Operation Temperature: -40° to +105°  
 Contact Material: Brass  
 Standard: PA6T  
 Insulator Material: Polyester (UL 94V-0)  
 Contact Plating: Gold Flash  
 Max. Processing Temp: 240° C for 30-60 seconds  
 (260° C for 5 seconds)



RECOMMEND P. C. B LAYOUT  
 PCB TOLERANCE: ±0.05 (TOP VIEW)



THIS DOCUMENT IS THE SOLE PROPERTY OF BBJconn Technology Co., Ltd. Corporation AND SHOULD NOT BE USED IN WHOLE OR IN PART WITHOUT PRIOR WRITTEN PERMISSION.		深圳市步步精科技有限公司 .X: ±0.38 X': ±3" .XX: ±0.25 X'': ±2" .XXX: ±0.13 XX': ±1"		NAME: 排母 2.0FH H6.35 3x4P 180度 PC2.8 Y型 空2.5.7.8.9.11P 盒装	
APPD.	JM_Zheng	PJ. NO.: FH.04.13-36-3001		SIZE: A4 DRW NO.:	
CHKD.	LYX	FINISH: SEE NOTES		MAT'L.: SEE NOTES	
PDWG.NO:	0266-1	DR.	SGF	SCALE: N/A	REV.: A0 UNIT: mm PAGE: 1/1